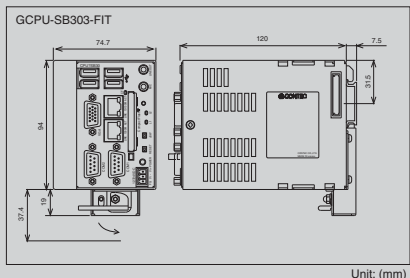


■ Specifications

Model	GCPU-SB303-FIT [CPU-SB303-FIT]	GCPU-SB303-FIT-3F [CPU-SB303-FIT-3F]
CPU	Ultra Low Voltage Intel® Celeron® Processor 800MHz (FSB400MHz)	
Chipset	Intel® 852GM+ICH4	
Memory	512MB, 1x 200-pin SO-DIMM socket, PC2100(DDR266) DDR SO-DIMM	
Compact Flash	1x CF CARD Type I, II (Primary IDE Master) CF on board (2GB, 1 partition)	
Wired LAN	LAN1: 1x 100BASE-TX/10BASE-T, RJ-45 connector (Built in Intel ICH4) LAN2: 1x 1000BASE-T, RJ-45 connector (Intel 82541P)	
Supported Resolution	640x480, 800x600, 1,024x768, 1,152x864, 1,280x600, 1,280x720, 1,280x960, 1,280x1,024, 1,400x1,050, 1,600x900, 1,600x1,200, 1,856x1,392, 1,920x1,080, 1,920x1,200(16,770,000 colors), 1,920x1,440(65,536 colors)	
CRT I/F	1 x Analog RGB (15-pin HD-SUB connector),	
Keyboard I/F	USB 2.0 **	
Mouse I/F	USB 2.0 **	
FDD I/F	USB 2.0 **	
IDE I/F	Secondary: Dedicated 40-pin, half-pitch connector on bottom of unit (for optional CD/DVD-ROM drive)	
Serial I/F	RS-232C(general-purpose): 2ch, 9 pin D-SUB male connector, Baud rate: 50~115,200bps	
USB I/F	4ch USB 2.0 compliant: (High / Full / Low Speed)	
F&EIT I/F	8 F&EIT series device modules can be connected (max) **3 (power consumption of external units cannot exceed 3.0A) Output: Line Out x1 (stereo output level 8 Ω200mW S/N ratio:90dB), Input: MICx1 (Monaural), Plug: Φ3.5 Stereo mini jack	
Audio	WDT: software programmable, 255 level (1sec to 255sec); RESET when time-up occurs	
RAS function	RTC/CMOS Lithium backup battery life: 10 years or more	
Supported OS	Windows XP Embedded Windows XP Professional Microsoft Windows 2000 Professional IBM PC-DOS 2000 Ver.7.0 Linux 2.6 kernel (TurboLinux 10 server)	Windows XP Embedded C drive (NTFS) [Space Used: 683MB, Space Free: 1.22GB] EWF partition [Space Used: 6MB]
Power Supply	12~24VDC	
Current Consumption (Max.)*6	12V: 2.4A / 24V: 1.3A	
Operating / Storage Temp / Humidity	0~50°C / -10~60°C / 10~90%RH (no condensation)	
Floating Dust Particles/Corrosive Gases	IP20 (Normal) / None	
Noise resistance	Static electricity Line-noise*5	Contact discharge / ±4kV (IEC61000-4-2Level2, EN61000-4-2Level2), Atmospheric Discharge / ±8kV (IEC61000-4-2Level3, EN61000-4-2Level3) AC line:±2kV, Signal line:±1kV (IEC61000-4-4Level3, EN61000-4-4Level3)
Vibration Resistance	Sweep Resistance	10~57Hz / semi-amplitude 0.15mm, 57~150Hz / 5.0G, 40 min. each in x, y, and z directions (JIS C60068-2-6, IEC60068-2-6 compliant)
Impact Resistance	15G, half-sine shock for 11 ms in x, y, and z directions (JIS C60068-2-27, IEC60068-2-27 compliant)	
Grounding	Class D grounding (previous class 3 grounding)	
Dimensions (mm)	74.7(W)x120.0(D)x94.0(H)	
Weight	800g (with DIN-rail mounting hardware: 900g)	
Notes	*1: Please use USB ports to connect keyboard / mouse / FDD *2: The total maximum power consumption of the modules cannot exceed the rated output current of the power supply *3: The stack connector supplies power to the device modules. The rated current of stack connector is 3.0A (max). *4: If the unit is mounted upside down and used in a high-temperature environment, even if the temperature is within the specified range, please add a fan to the system configuration. *5: When using AC-DC power unit PBA79F-24 (Mitr. - Corsel Company) *6: When using with device modules, CONTEC recommends using a power supply with a minimum of 70W. When using only the main unit, a power supply of 50W(min) is recommended. The following DIN-rail mountable power supplies are recommended - DLP75-24-1 (75W / Mitr. - Densei-lambda), P5SR-SD24 (60W / Mitr. - IDEC), SBVS-06024 (60W / Mitr. - OMRON)	

Dimensions



Unit: (mm)

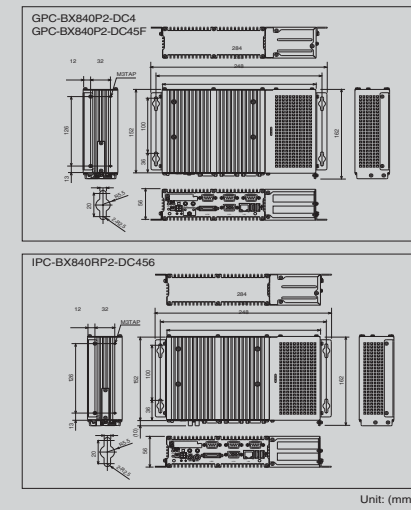
■ Specifications

Model	GPC-BX840P2-DC4 [IPC-BX840P2-DC400]	GPC-BX840P2-DC45F [IPC-BX840P2-DC45F]	IPC-BX840P2-DC456
CPU	Ultra Low Voltage Intel® Celeron® Processor 800MHz (FSB400MHz)		
Chipset	Intel® 852GM+ICH4		
Memory	512MB, 1x 200-pin SO-DIMM socket, PC2100(DDR266) DDR SO-DIMM		
PC Card slot	-		
Compact Flash	1x CF CARD Type I (dedicated to memory card), bootable (PrimaryMaster, PrimarySlave switch-able)		
Wired Card slot	-		
Wired LAN I/F	1x 100BASE-TX/10BASE-T, RJ-45 connector		
Wireless LAN Controller	Built in Intel ICH4		
Wireless LAN	IEEE802.11a/b/g compliant (see complete Wireless specs.below)		
Expansion slots	2x Low Profile PCIslots, Installable size: 140(L) x 63.41(H) mm		
Supported Resolution	640x480(16,770,000 colors), 800x600(16,770,000 colors), 1,024x768(16,770,000 colors), 1,280x1,024(16,770,000 colors), 1,600x1,200(16,770,000 colors)*2		
CRT I/F	1 x Analog RGB (15-pin HD-SUB connector)		
LCD I/F	1 x LVDS (26-pin Half-pitch connector)		
Keyboard I/F	USB 2.0 *3		
Mouse I/F	USB 2.0 *3		
FDD I/F	USB 2.0 *3		
IDE I/F	36-pin Half Pitch connector located on left side (for connection of CD/DVD-ROM using optional cable)		
Serial I/F	3ch RS-232C (general-purpose) / Serial ports 1, 2, 3 / 9 pin D-SUB male connector / Baud rate: 50~115,200bps 1ch for touch panel / Serial port 4 (inside LVDS connector); 1ch for microcontroller communication / Serial port 5 *4		
Parallel I/F	-		
USB I/F	2ch USB 2.0 compliant		
General-purpose I/O	-		
Audio	AC97 compliant; Line Out: Φ3.5 Stereo mini jack, Full-scale output level 1.5Vrms(Typ.), Dual 50mW Amplifier; MIC Input: Φ3.5 Stereo mini jack, Full-scale output level 1.6Vrms(Typ.)		
RAS function	WDT: software programmable, 255 level (1sec to 255sec); RESET when time-up occurs		
RTC/CMOS	Lithium backup battery life: 10 years or more, RTC precision (25°C): ±3 min. per month (RTC included in the ICH4)		
Supported OS	Windows XP Embedded		
Power Supply	12~24VDC ±5%		
Current Consumption (Max.)	12V 2.2A / 24V 1.1A		
Power Outage	-		
Dielectric Strength	-		
Operating / Storage Temp / Humidity	0~50°C *6 / -10~60°C / 10~90%RH (no condensation)		
Floating Dust Particles/Corrosive Gases	IP20 (Normal) / None		
Noise resistance	Static electricity Line-noise	Contact discharge / ±4kV (IEC61000-4-2Level2, EN61000-4-2Level2), Atmospheric Discharge / ±8kV (IEC61000-4-2Level3, EN61000-4-2Level3) AC line:±2kV, Signal line:±1kV (IEC61000-4-4Level3, EN61000-4-4Level3)	
Vibration Resistance	Sweep Resistance	10~57Hz / semi-amplitude 0.375mm 57~500Hz / 5.0G, 60 min. each in x, y, and z directions (JIS C60068-2-6, IEC60068-2-6 compliant)	
Impact Resistance	15G, half-sine shock for 11 ms in x, y, and z directions (JIS C60068-2-27, IEC60068-2-27 compliant)		
Grounding	Class D grounding (previous class 3 grounding)		
Dimensions (mm)	251(W)x152(D)x56(H)		
Weight	Approx. 2.0kg		
Notes	*1: CF size is calculated based on 100,000,000 byte = 1GB. Capacity recognized by the OS may sometimes be less than the actual value. *2: Not supported by LVDS I/F. *3: Use USB ports to connect keyboard / mouse *4: For internal system use - not user accessible *5: If used in a high-temperature environment, even if the temperature is within the specified range, please add a fan to the system configuration.		

■ Wireless LAN Specifications

Model	IPC-BX840P2-DC456
Wireless LAN	IEEE802.11a
Interface type	IEEE802.11a-compliant OFDM (Orthogonal Frequency Division Multiplexing)
Channel	12ch (34.38, 42.46ch [US]; 38.40, 44.48ch [W5]; 52.56, 60.64ch [W53])
Data Speed*7	54, 48, 36, 24, 18, 12, 9, 6Mbps
Access Method	CSMA/CA + ACK (RTS/CTS)
Wireless LAN category	Low-power Data Transmission System (5.150~5.350GHz)
Aerial Power	10Mw/MHz or less
Security	WEP, WPA(AES, TKIP), WPA-PSK(AES, TKIP), WSL(above methods can be used simultaneously), IEEE802.1X
Wireless LAN	IEEE802.11b
Interface type	IEEE802.11b-compliant DSSS (Direct Sequence Spread Spectrum)
Channel	14ch (1~14)
Data Speed*7	11, 5.5, 2, 1Mbps (automatic)
Access Method	CSMA/CA + ACK (RTS/CTS)
Wireless LAN category	Low-power Data Transmission System (2.4~2.487GHz)
Aerial Power	10Mw/MHz or less
Security	WEP, WPA(AES, TKIP), WPA-PSK(AES, TKIP), WSL(above methods can be used simultaneously), IEEE802.1X
Wireless LAN	IEEE802.11g
Interface type	IEEE802.11g-compliant OFDM (Orthogonal Frequency Division Multiplexing)
Channel	13ch (1~13)
Data Speed*7	54, 48, 36, 24, 18, 12, 9, 6Mbps (automatic)
Access Method	CSMA/CA + ACK (RTS/CTS)
Wireless LAN category	Low-power Data Transmission System (2.4~2.487GHz)
Aerial Power	10Mw/MHz or less
Security	WEP, WPA(AES, TKIP), WPA-PSK(AES, TKIP), WSL(above methods can be used simultaneously), IEEE802.1X

Dimensions



Unit: (mm)